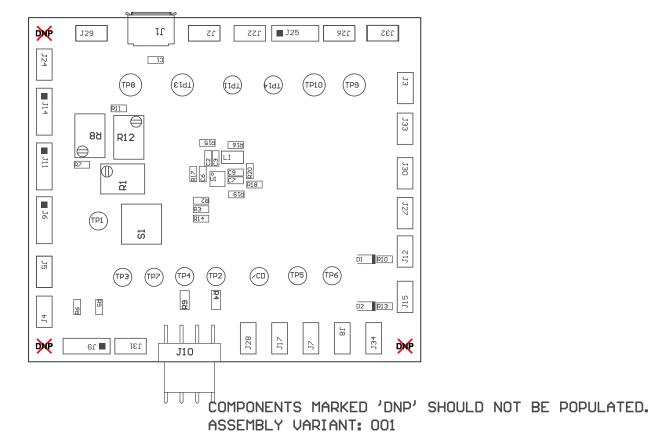
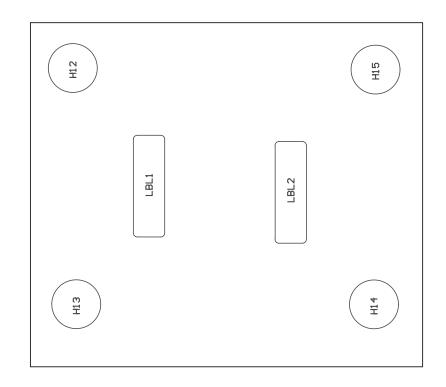
- ZZ1 Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.
- ZZ5 Tape Coil, RX into bottom of case, CENTERED, coil side down, lead wires passing through milled groove
- ZZ6 Install PCB in Case using #4 x 3/8 screws, inserting 0.1 thick spacers between PCB and case
- ZZ7
 The value of R2 + R6 can be adjusted to 250-ohms for WPC 1.1 requirements (FOD calibration only for this EVM)
- ZZ2 These assemblies are ESD sensitive, ESD precautions shall be observed.
- ZZ3 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- ZZ4 These assemblies must comply with workmanship standards IPC-A-610 Class 2., unless otherwise specified.



PCB VIEWED FROM TOP SIDE	BOARD #: PWR731	REV: A	SVN REV	: Not In VersionControl		
	TID #: .TID					
PLOT NAME = Top Assembly Drawing	GENERATED : 7/21/2	2015 4:46:42	PM	TEXAS INSTRUMENTS		



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PWR731	REV: A	SVN REV: Not	In VersionControl		
	TID #: PWR731					
PLOT NAME = Bottom Assembly Drawing	GENERATED : 7/21/2	015 4:46:44	PM 1	EXAS INSTRUMENTS		

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